

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

IN RE APPLICATION OF:

Lee CHEN, et al.

GROUP: 1763

SERIAL NO: 10/517,764

FILED: December 23, 2004

EXAMINER: OLSEN, ALLAN W

FOR: ANISOTROPIC DRY ETCHING OF CU-CONTAINING LAYERS

**SUBMISSION OF SUPPLEMENTAL APPLICATION DATA SHEET**

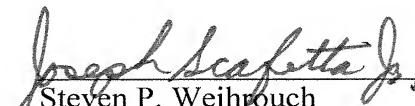
Office of Initial Patent Examination  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Applicant(s) submit herewith a Supplemental Application Data Sheet for the above-identified application for the purpose of correcting the 1<sup>st</sup> inventor's city of residence and his mailing address.

Respectfully Submitted,

OBLON, SPIVAK, McCLELLAND,  
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